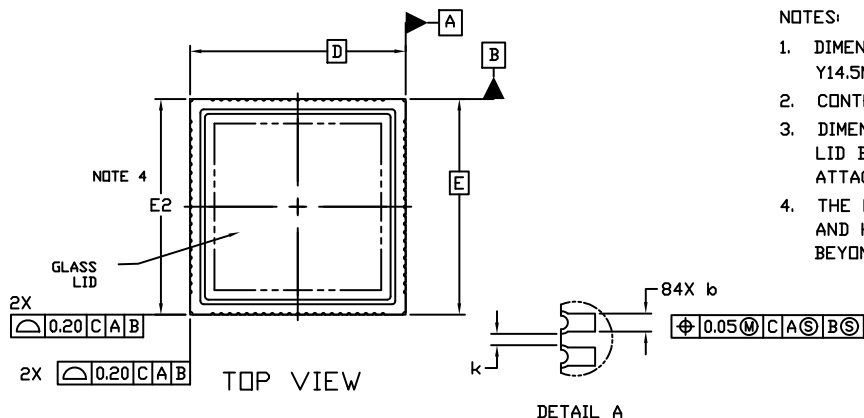




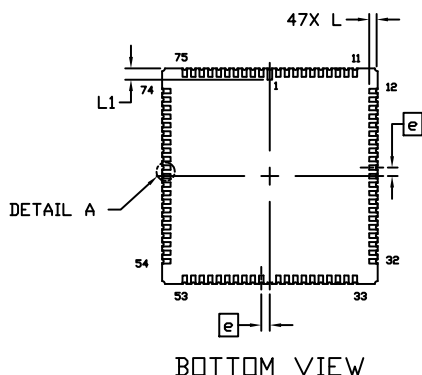
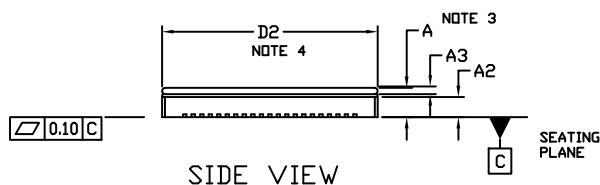
LCC84, 19x19
CASE 115BC
ISSUE A

DATE 26 JUN 2015

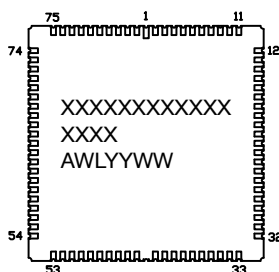


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
 4. THE LID IS DEFINED BY DIMENSIONS D2 AND E2 AND HAS A MAXIMUM ALLOWABLE SHIFT OF 0.60 BEYOND DIMENSIONS D AND E.

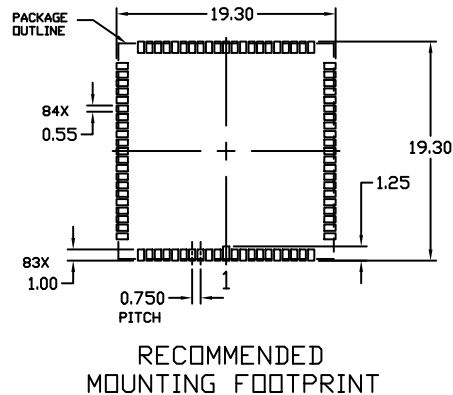
DIM	MILLIMETERS	
	MIN.	MAX.
A	2.08	2.74
A2	1.78	REF
A3	0.55	REF
b	0.32	0.48
D	19.00	BSC
D2	19.00	REF
E	19.00	BSC
E2	19.00	REF
e	0.75	BSC
k	0.12	---
L	0.62	0.88
L1	1.00	REF



GENERIC MARKING DIAGRAM



XXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 YY = Year
 WW = Work Week



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DESCRIPTION:	LCC84, 19.00 X 19.00	PAGE 1 OF 1

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